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# EITF35: Introduction to Structured VLSI Design

Part 1.1.2: Introduction (Digital VLSI Systems)

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# Outline

## □ Why Digital?

- Advantages
- Applications

## □ History & Roadmap

## □ Device Technology & Platforms

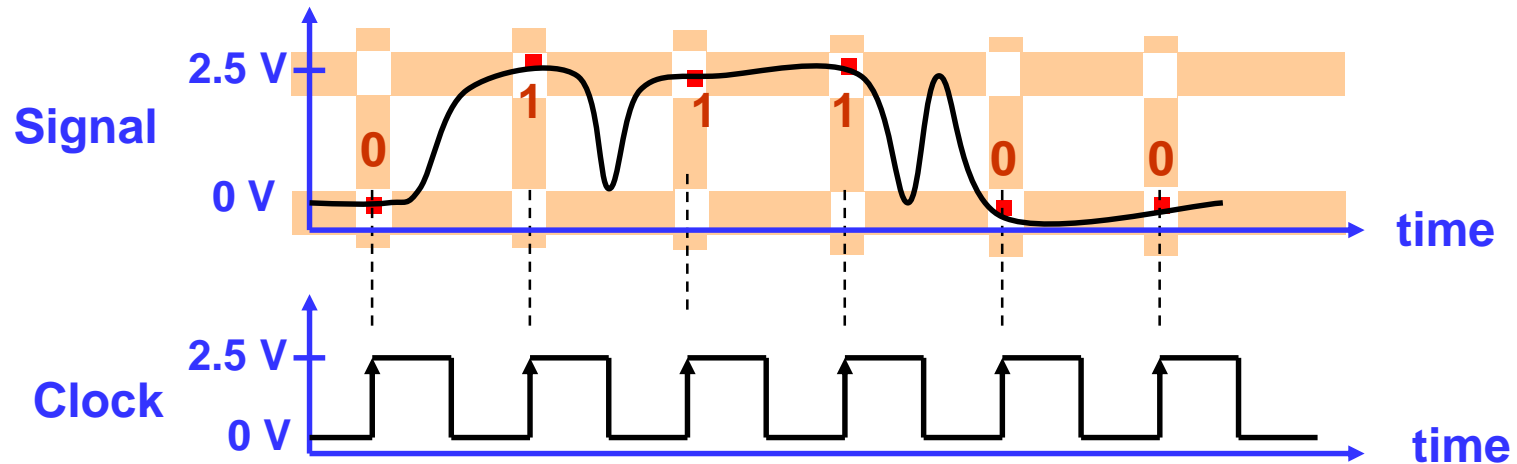
## □ System Representation

## □ Design Flow

## □ RTL (register transfer level) Basics



# Digitalization



## □ Digital is an abstraction

- Discrete in time: **Sampling**
- Discrete in value: **Quantization**

## □ Digital vs. Analog

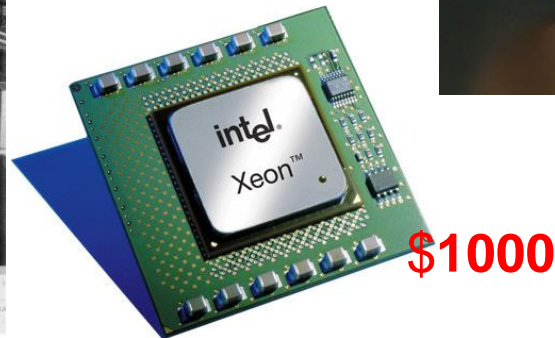
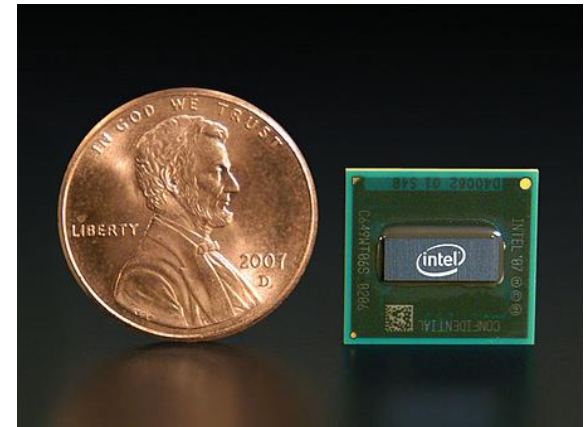
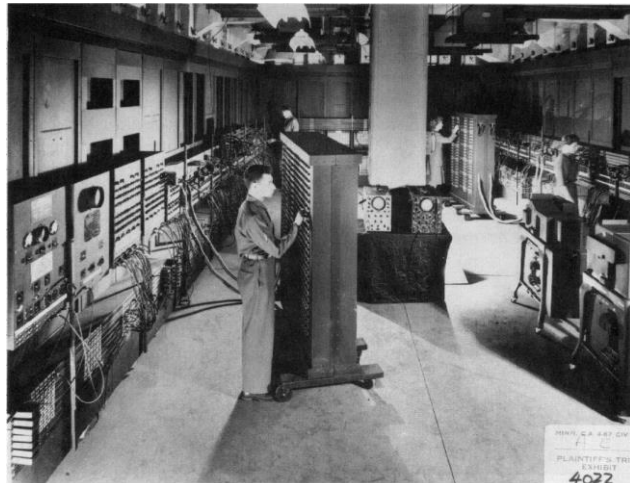
- Flexibility & functionality: easier to store and manipulate information
- Reliability: tolerant to noise, mismatch, variations, etc.
- Economic: “easy” to design, and friendly to technology evolution



# Applications 4C: CCCC



## Computation



# Applications: CCCC



## Communication

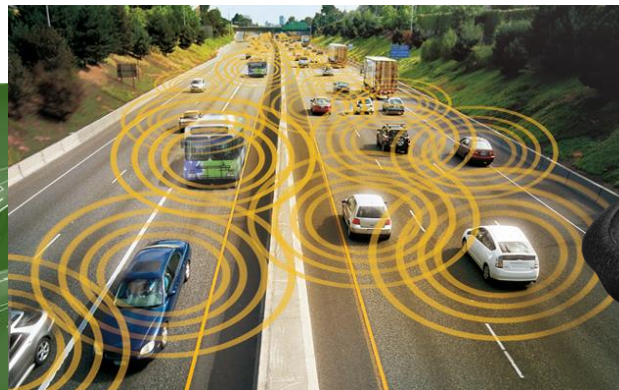




# Applications: CCCC



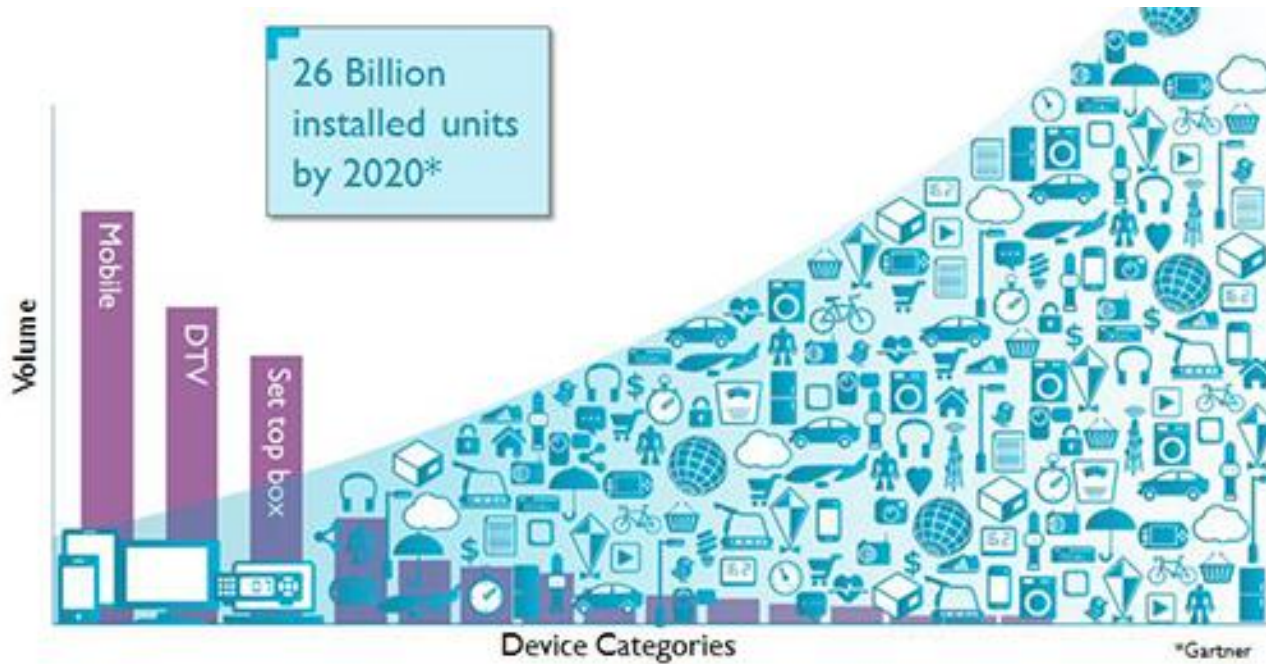
*Consumer*



*Control*



# Tomorrow



# Outline

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# Brief History

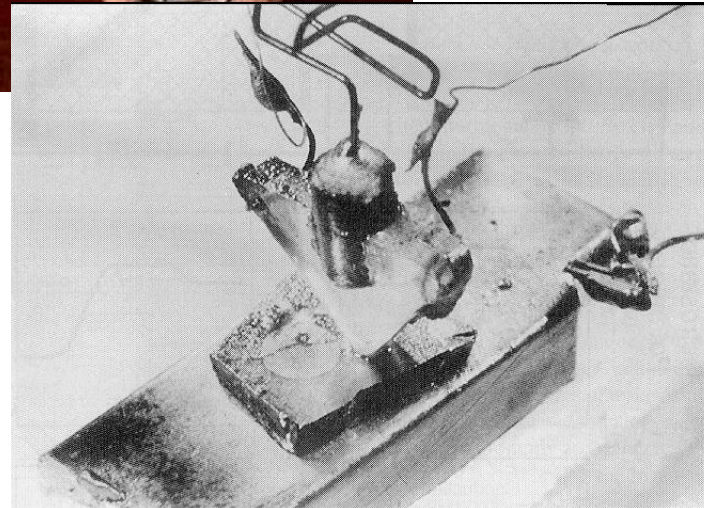
## □ Transistor Evolution

- First Transistor
  - *Bell Labs (1947)*
  - *Bardeen, Brattain, Shockley*
  - *Nobel Prize (1956)*



## □ Integration Evolution

- First Integrated circuit
  - *Jack Kilby*
  - *TI (1960)*
  - *Nobel Prize (2000)*



Material ...  
of the  
ely



# Technology Evolution

## □ Bipolar

- Transistor
  - 1947, *Bardeen/Bell Lab*
- Bipolar junction transistor
  - 1949, *William Shockley*
- Logic gate
  - 1956, *Harris*
- Integrated circuit
  - 1958, *Kilby/Noyes*
- Transistor–transistor logic (TTL)
  - 1962, *James L. Buie*
- High-speed Emitter-coupled logic (ECL)
  - 1974, *Masaki*

## □ MOSFET (metal-oxide-semiconductor field-effect transistor )

- Bipolar faces **power** and **size** limitation
- **CMOS logic gate**
  - 1963, *Wanlass*
- PMOSFET
  - 1970, *first practical MOS IC, Calculator*
- NMOSFET
  - 1970, *high-density storay(4K)*
  - 1972, *first microprocessor(4004)*
  - 1974, *8080 microprocessor*



# Technology Evolution (cont.)

## □ Main trend today

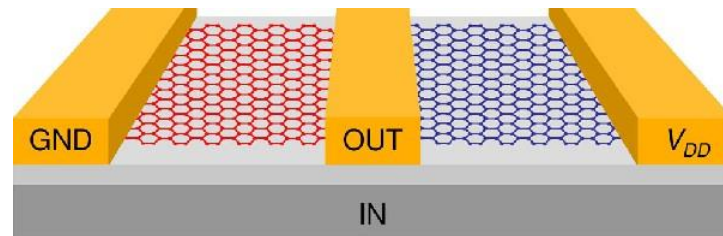
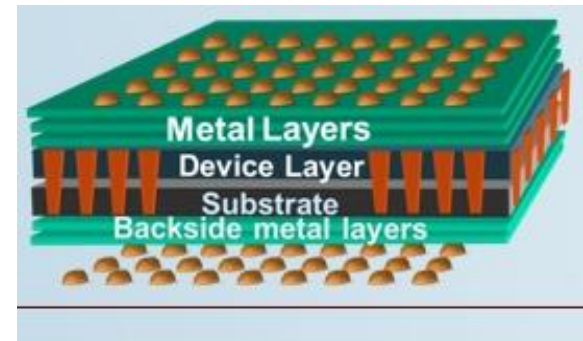
- Since early 80' s until today, **CMOS** became dominant

## □ For higher performance, other technologies are used

- Bi-CMOS (bipolar-CMOS): High speed memory and gate arrays
- ECL (Emitter-coupled logic): Even higher performance

## □ What's Next?

- **3D-IC, FinFET**
- Integrated photonics circuit
- Superconducting electronics
- Quantum circuit
- **Graphene circuit**



# Moore's Law

The experts look ahead

## Cramming more components onto integrated circuits

With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squeezing as many as 65,000 components on a single silicon chip

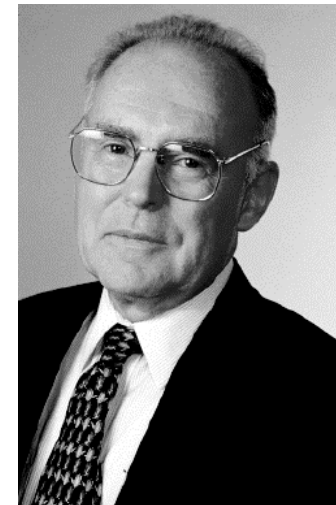
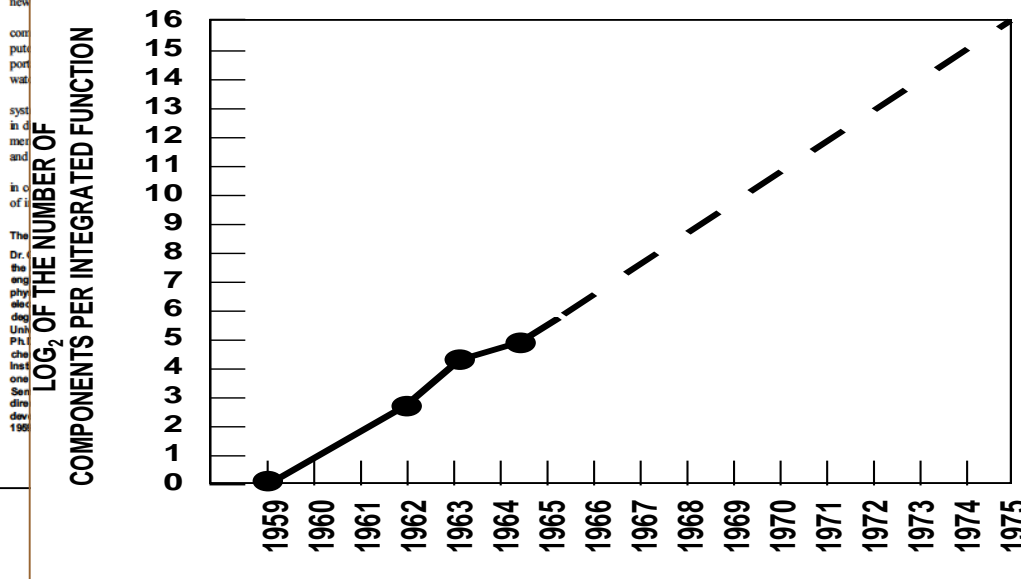
By Gordon E. Moore

Director, Research and Development Laboratories, Fairchild Semiconductor division of Fairchild Camera and Instrument Corp.

The future of integrated electronics is the future of electronics itself. The advantages of integration will bring about a proliferation of electronics, pushing this science into many new machine instead of being concentrated in a central unit. In addition, the improved reliability made possible by integrated circuits will allow the construction of larger processing units.

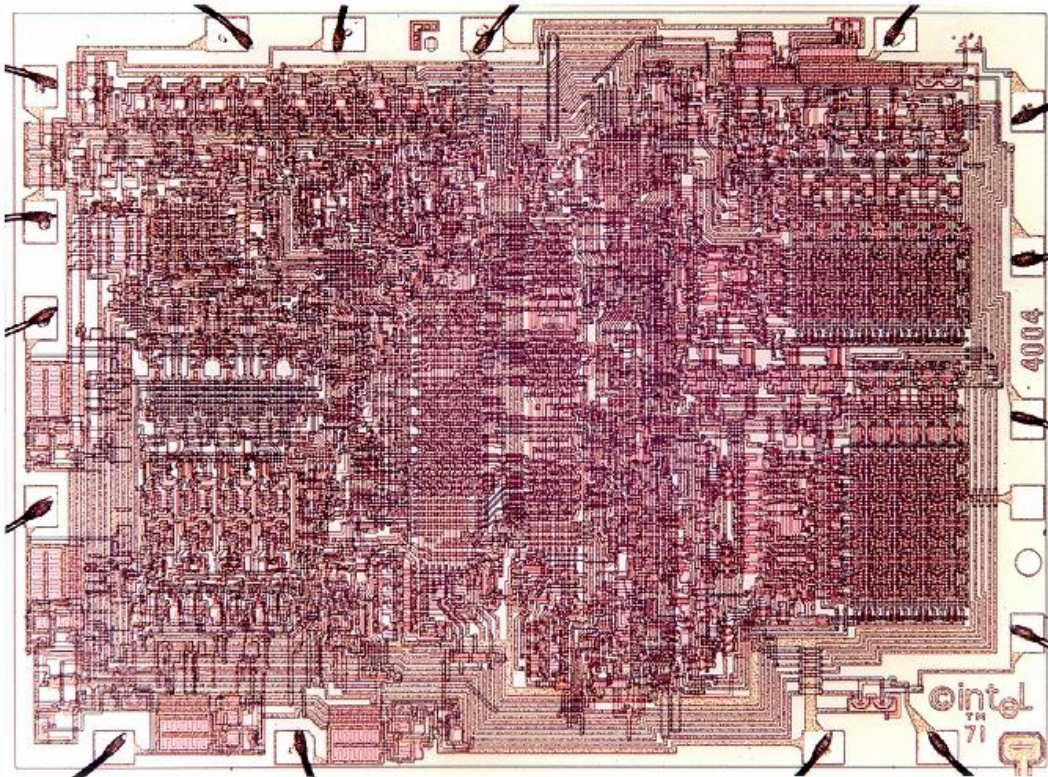
## □ Electronics, Apr. 19, 1965

*Gordon Moore (co-founder of Intel) made a prediction that semiconductor technology will double its effectiveness every 18 months*





# Intel 4004:1972



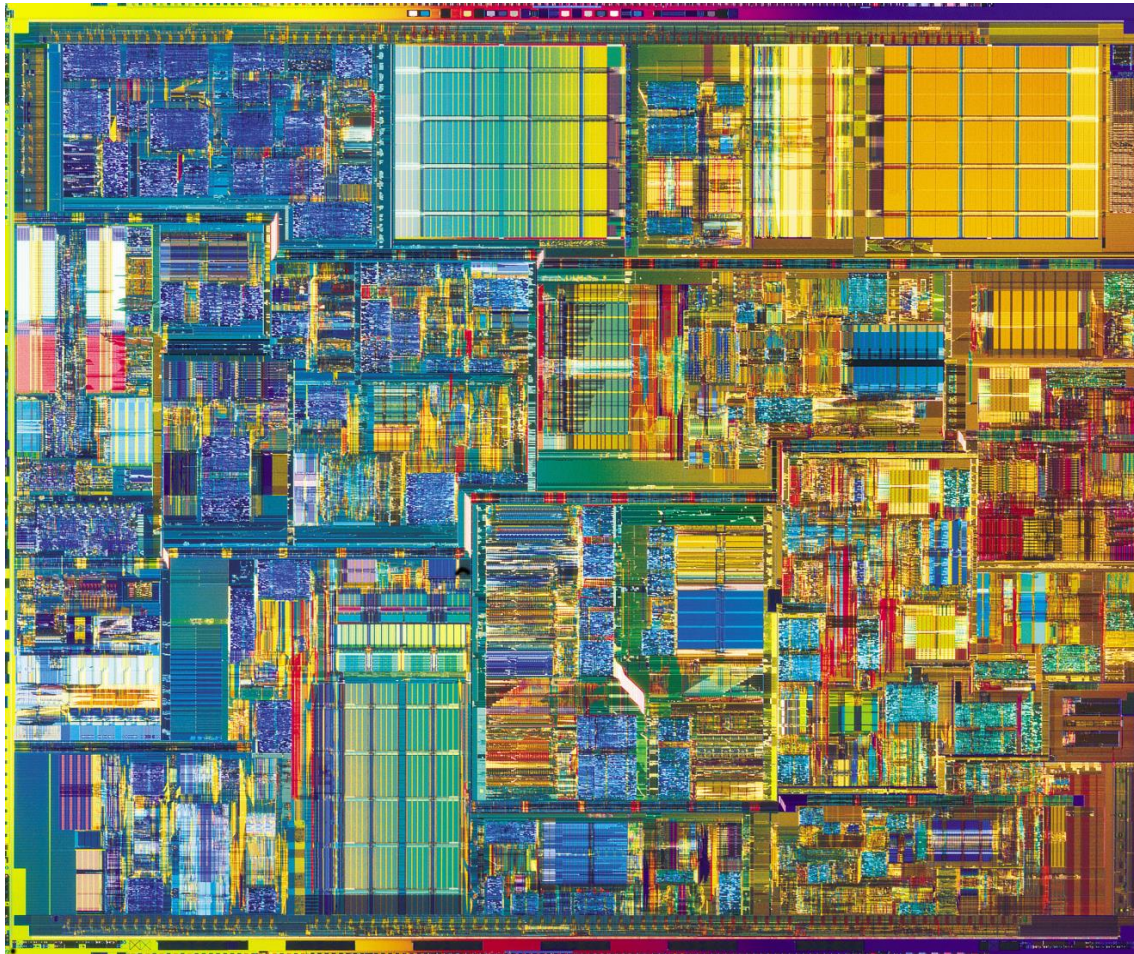
- First micro-processor on a single chip
- 2 300 transistors
- 0.3 mm x 0.4 mm
- 4 bit words
- Clock: 0.108 MHz

*You will have the possibility to design a more powerful processor in one of our courses*





# Intel Pentium 4 (2000)



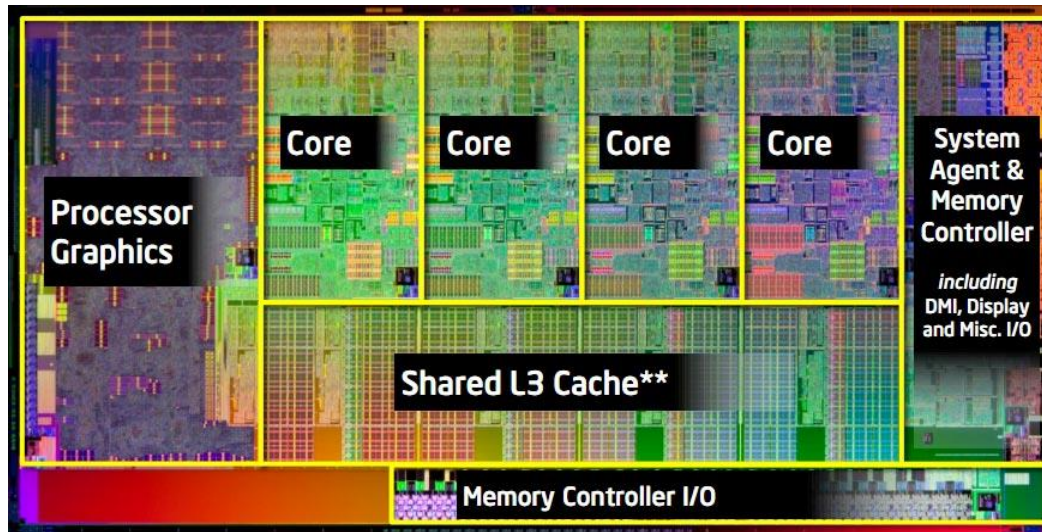
- ❑ 42 000 000 transistors
- ❑ 0.18 micron CMOS
- ❑ Clock: 1.5 GHz
- ❑ Die: 20 mm<sup>2</sup>

*Baseband ASIC of a modern mobile phone has easily 10 times more transistors.*



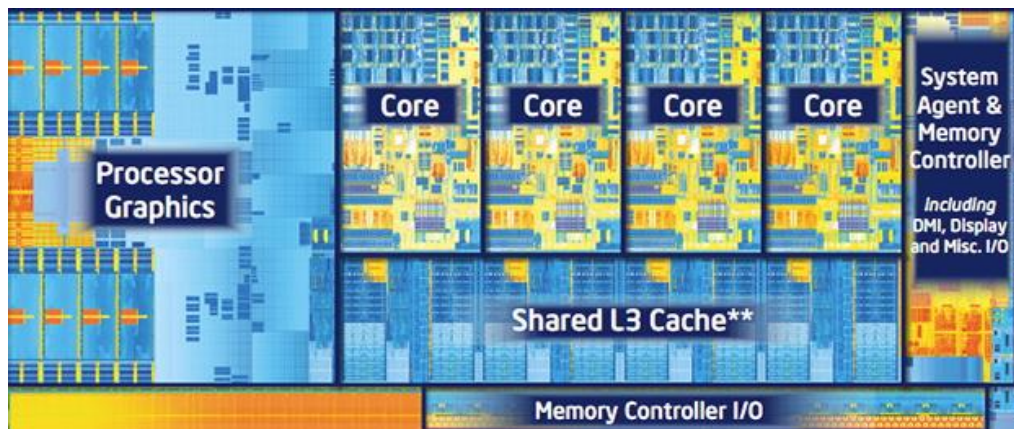


# SandyBridge (2009)



- 32 nm-64 bit
- 995 000 000 Transistors (**23 × P4**)
- ~**3.5 GHz**
- 216 mm<sup>2</sup>

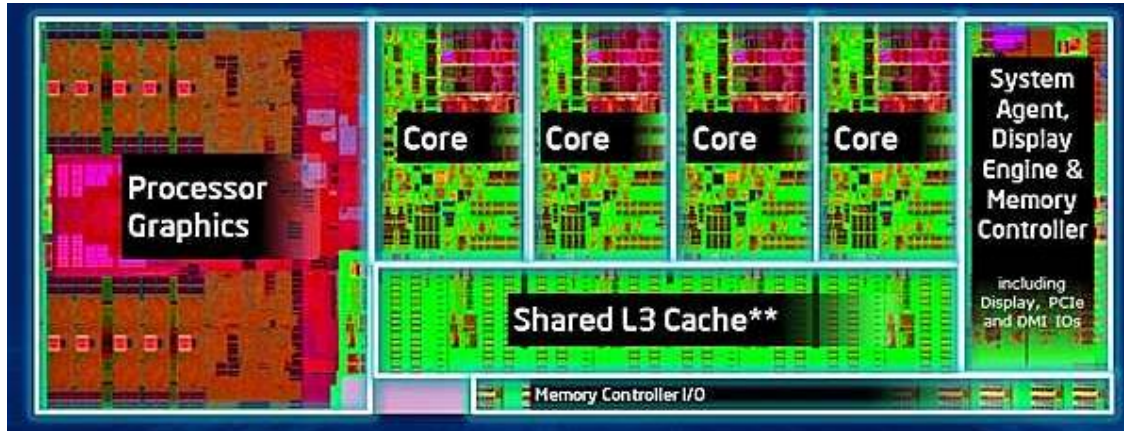
# IvyBridge (2011)



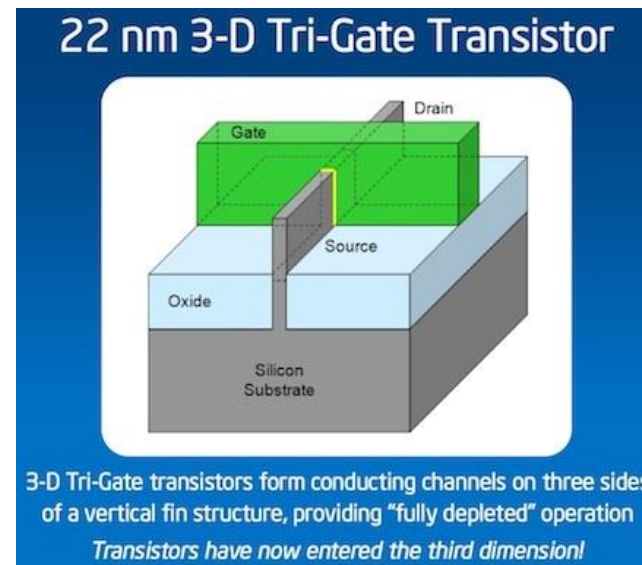
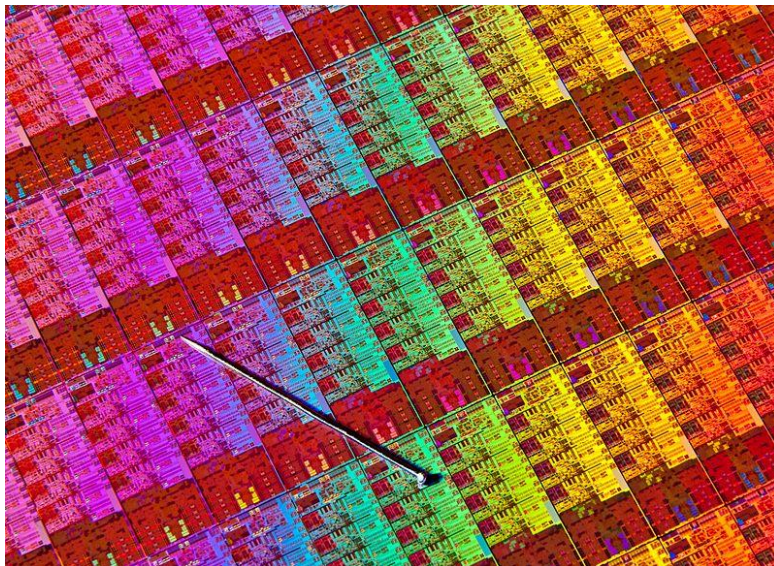
- 22 nm-64 bit
- 1.4b Transistors
- ~**3.5 GHz**
- 160 mm<sup>2</sup>



# Haswell (2013)



- 22 nm
- **Tri-gate 3D transistor**
- **1.4b Transistors**
- **~3.5 GHz**
- **177 mm<sup>2</sup>**





# Braswell (2015)



The diagram is set against a blue background. On the left, a vertical double-headed blue arrow indicates a spectrum. At the top, the word 'Today' is positioned above two processor images: a blue Haswell chip and a silver Broadwell chip. At the bottom, the word 'Future' is positioned above two processor images: a blue Bay Trail chip and a blue Braswell chip. Below the processor images are four icons: the Android robot, the Chrome logo, the Linux Tux penguin, and the Windows logo. To the right of the processor images, the text '5th Generation Core™ Processors' is written in yellow. Below this, three lines of white text describe the processors: 'Industry Leading 14nm', 'Fanless 2 in 1s to Enthusiast Desktops', and 'Amazing Form Factors'. At the bottom right, the text 'New User Experiences' is written in white, followed by 'Source: Intel' in bold black text.

Today

Future

intel Haswell

intel Broadwell

intel Bay Trail

intel Braswell

5th Generation Core™ Processors

Industry Leading 14nm

Fanless 2 in 1s to Enthusiast Desktops

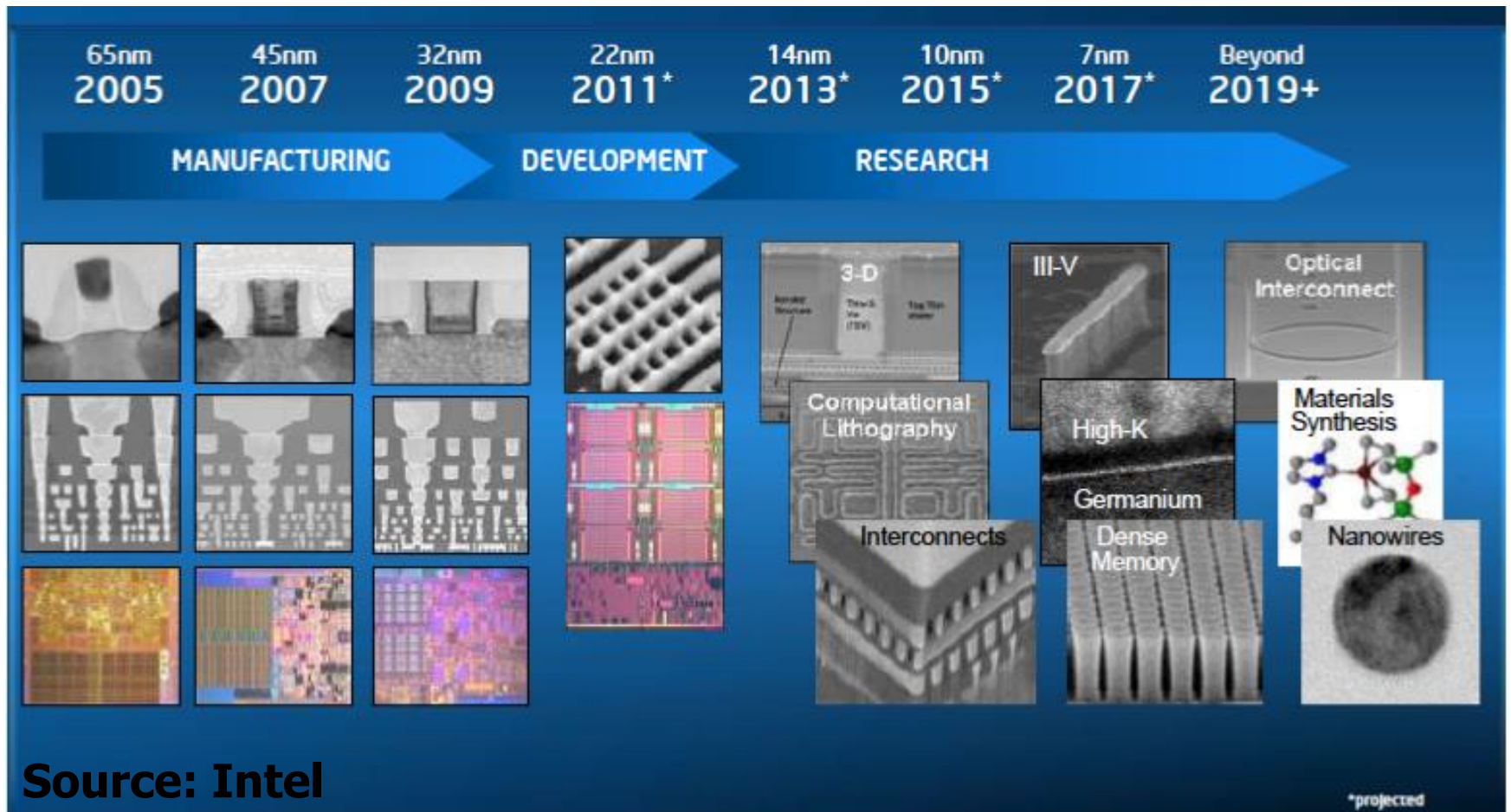
Amazing Form Factors

New User Experiences

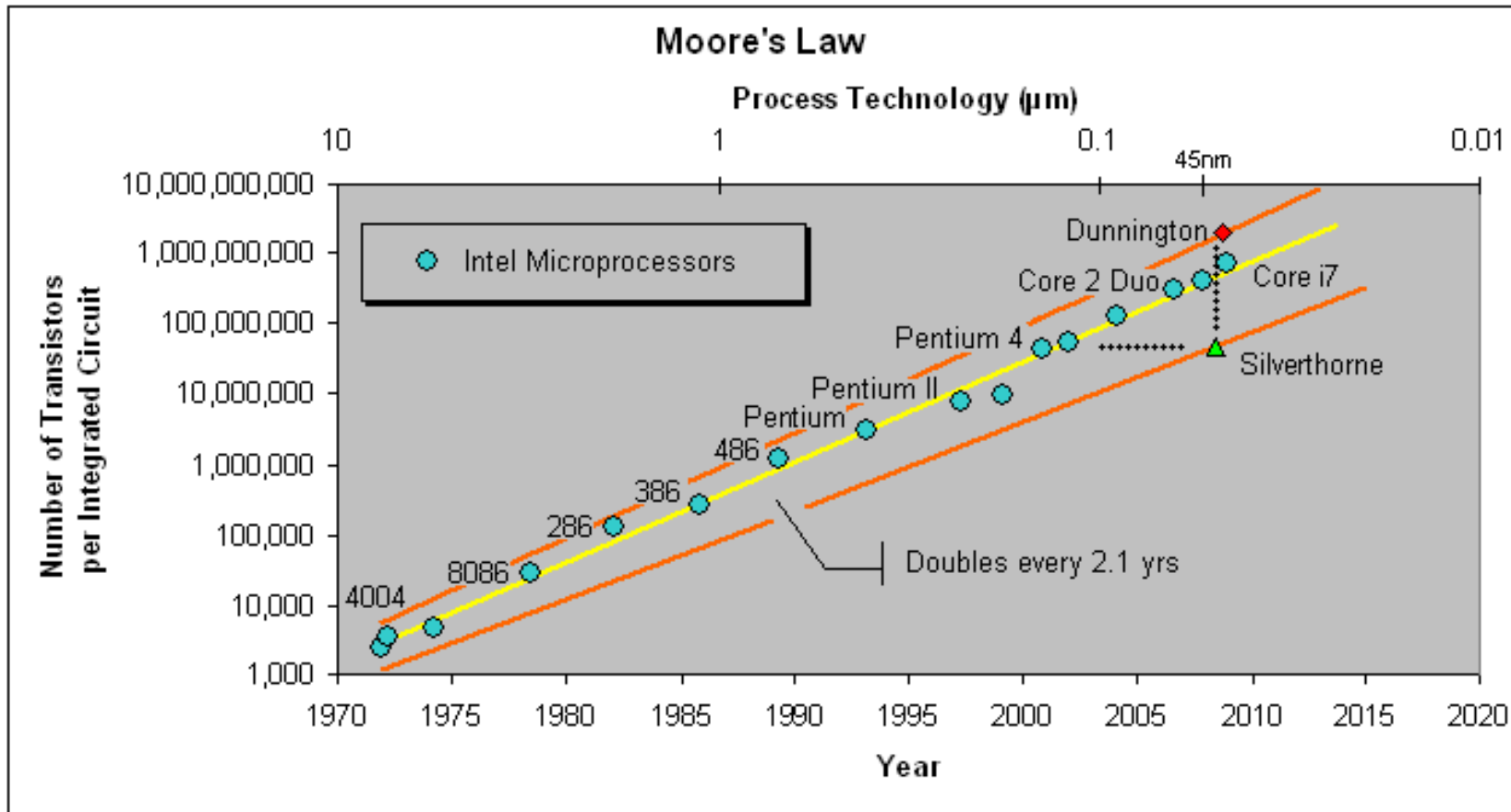
**Source: Intel**



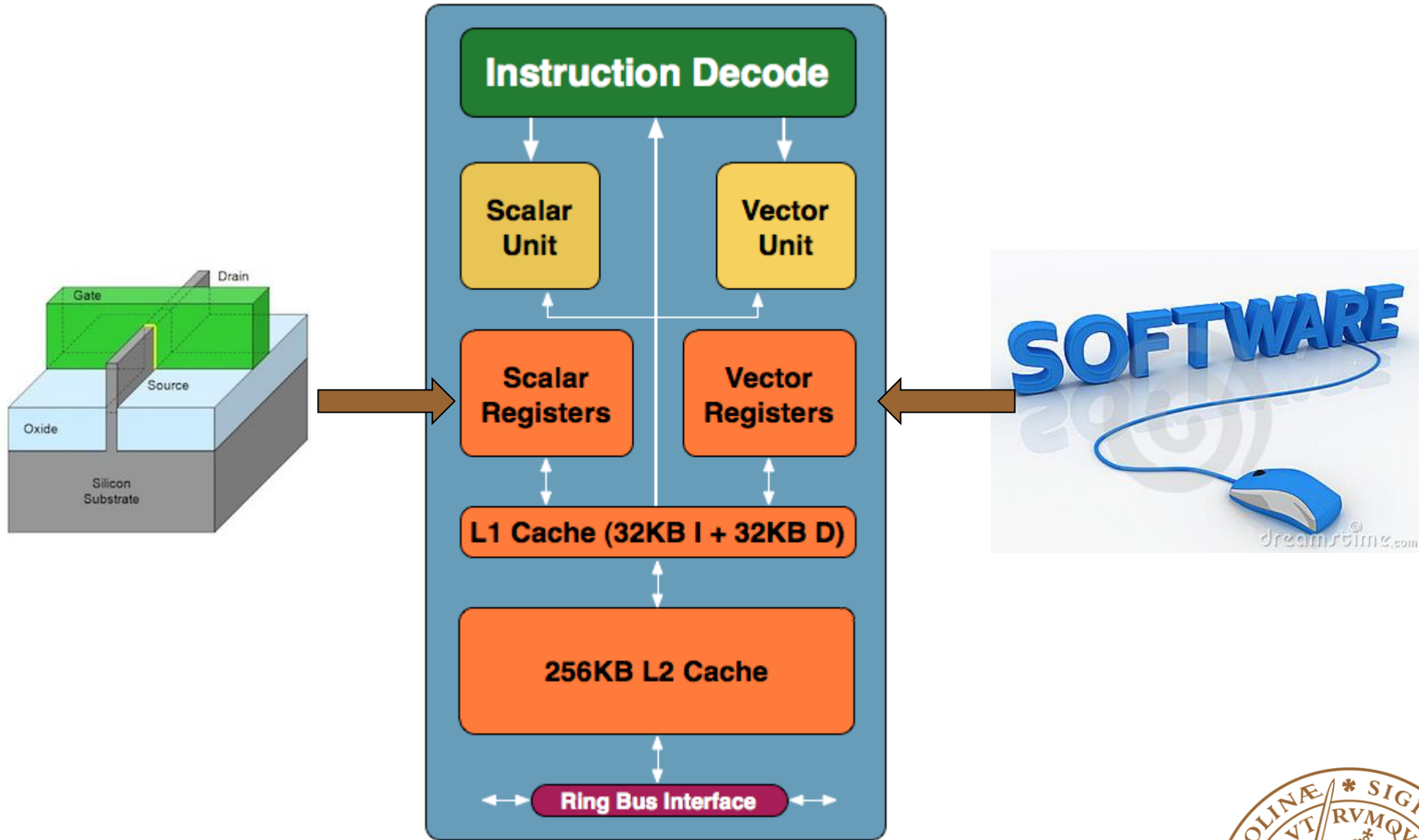
# On-Time 2 Year Cycles



# Moore's Law: number of transistors



# X86 Architecture



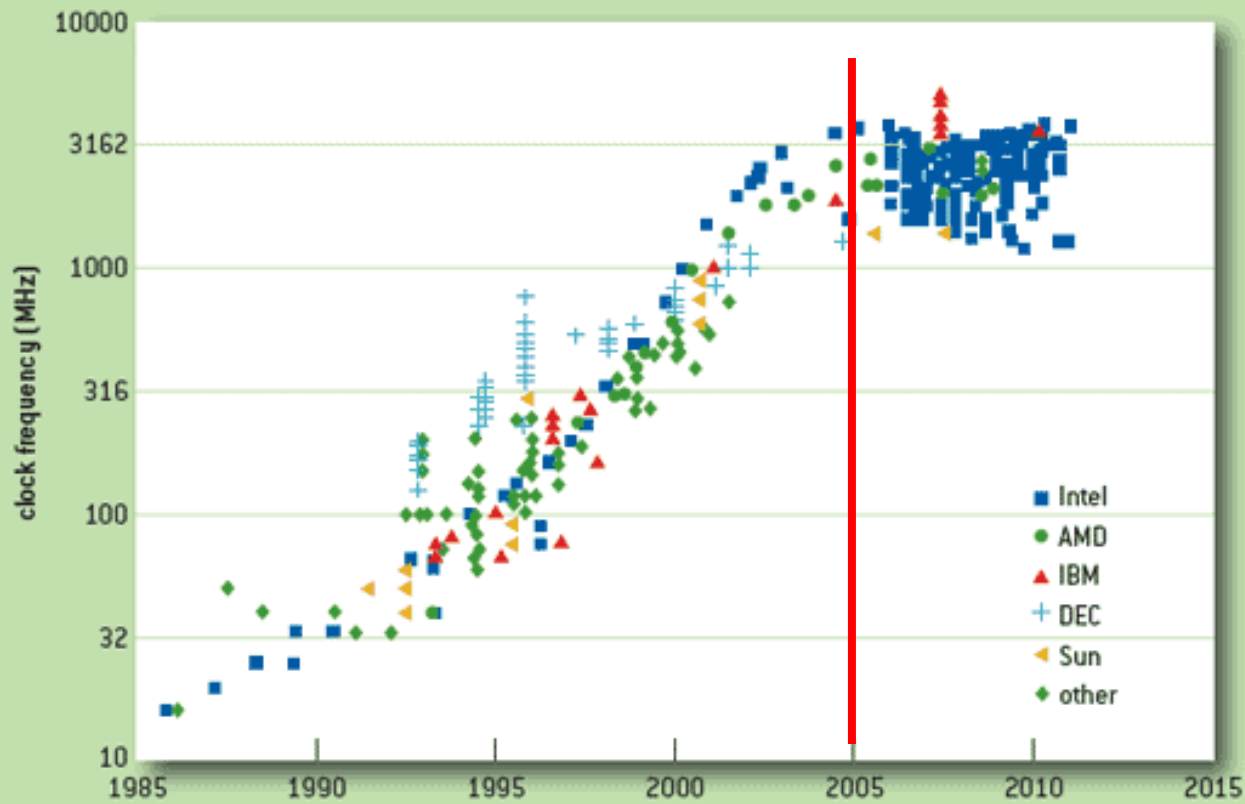


# Moore's Law: frequency

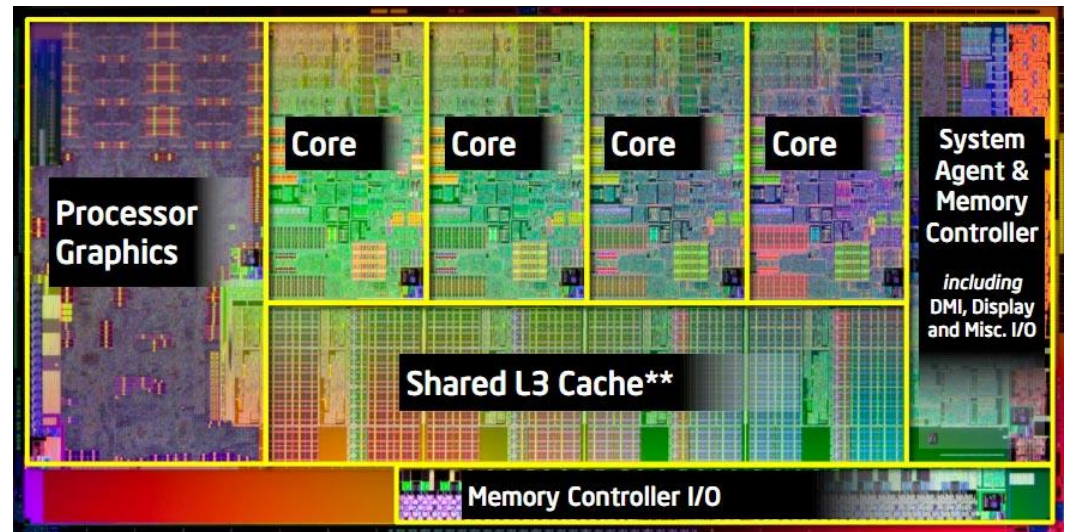
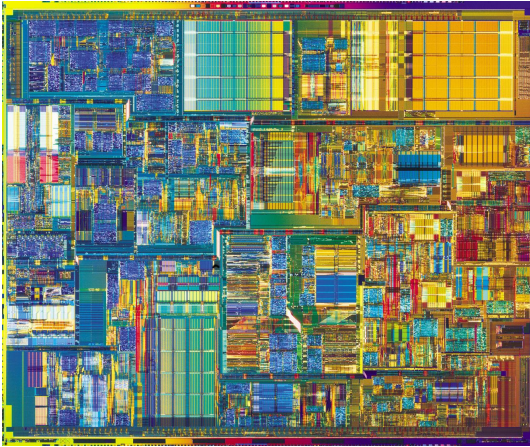
FIGURE 7

Source: CPU DB: Recording Microprocessor History

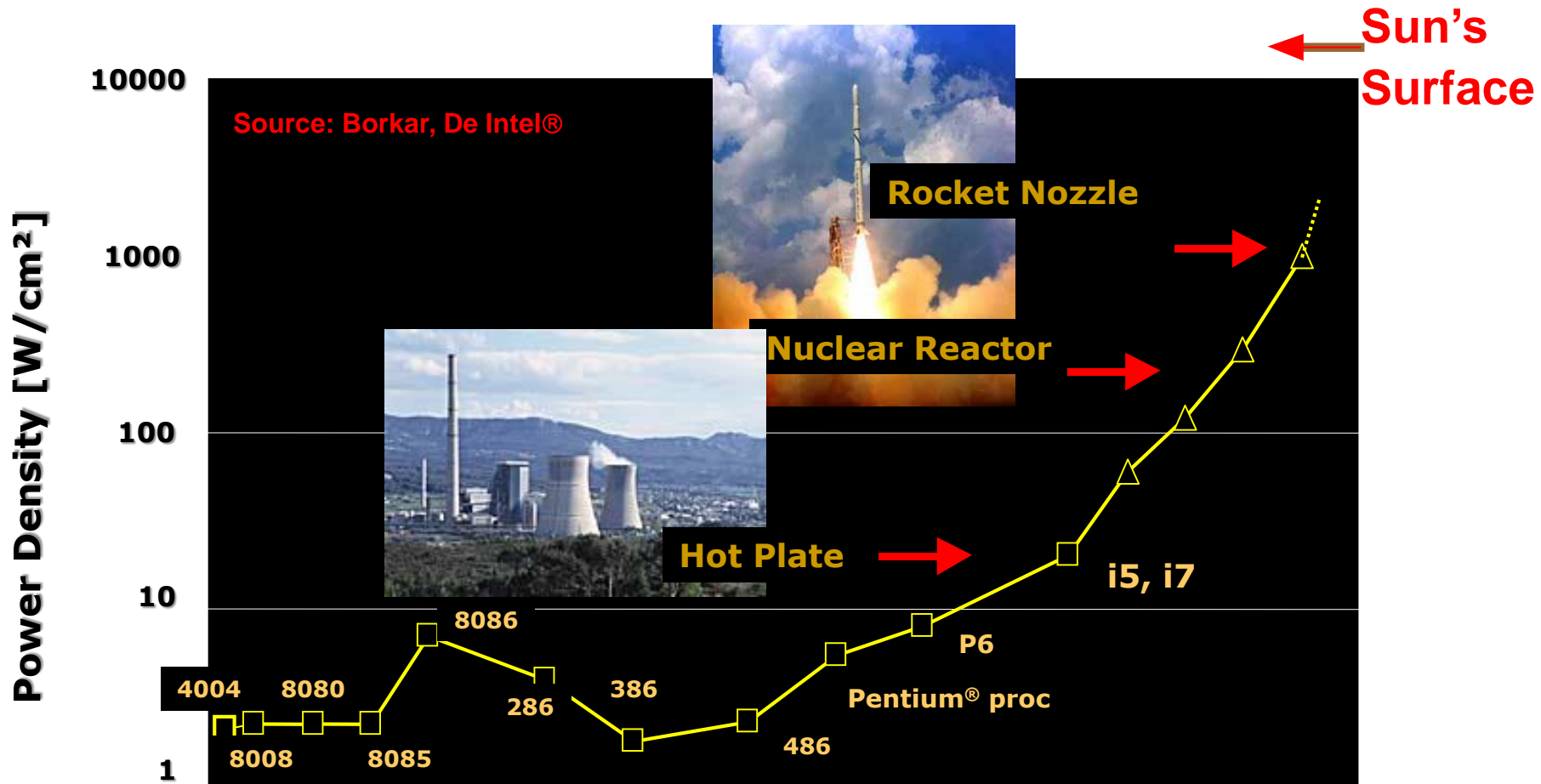
Processor Frequency Scaling Over Time



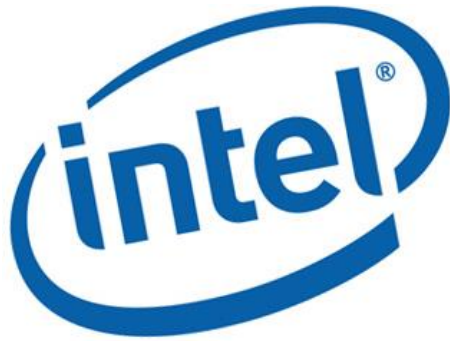
# Architecture change due to physic limitation



# Moore's Law: power density



# Architecture change due to new applications



# ARM





# Outline

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## □ **Device Technology & Platforms**

## □ System Representation

## □ Design Flow

## □ RTL Basics



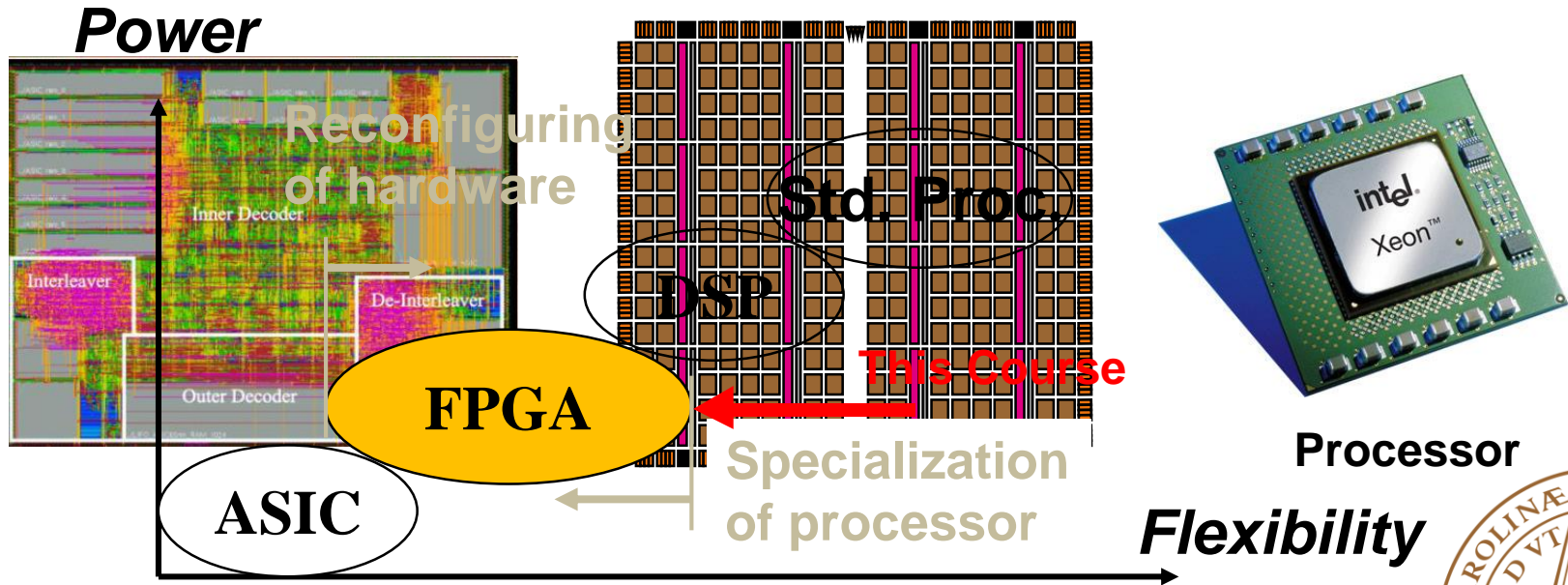
# Devices

## □ General-purpose integrated circuits

- **Microprocessors**, digital signal processors, **FPGA** and memories

## □ Application-specific integrated circuits (ASIC)

- Designed for a narrow range of applications
- Full-custom ASIC
- **Standard-cell ASIC**



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# System Representation

## □ System

- SoC: a CPU chip ...

## □ Module

- Macro cell in a chip: ALU...

## □ Gate

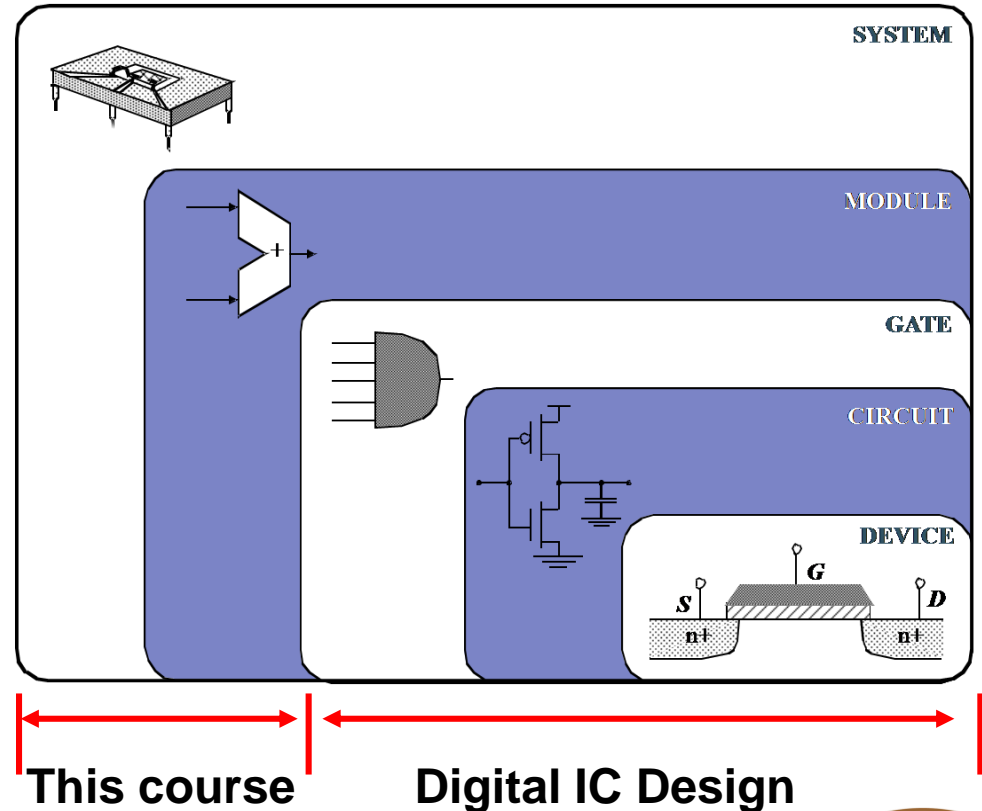
- Basic logic block: xor, nor...

## □ Circuit

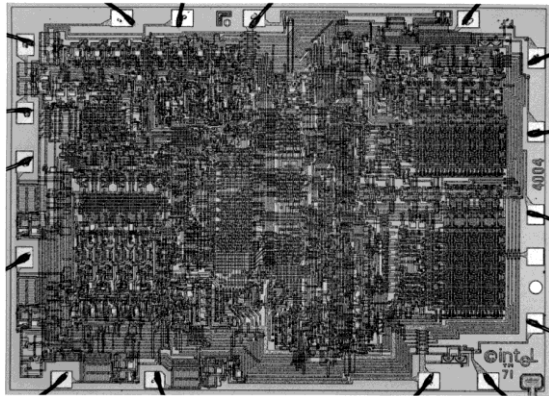
- Transistors

## □ Device

- Gate, source, drain

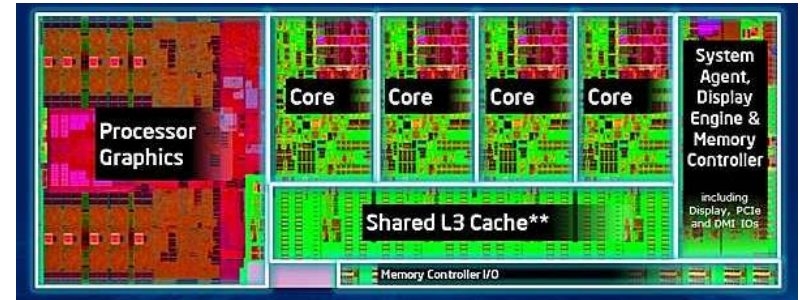


# View a Design in a Proper Way



Intel 4004 (2.3K transistors)

Full-custom

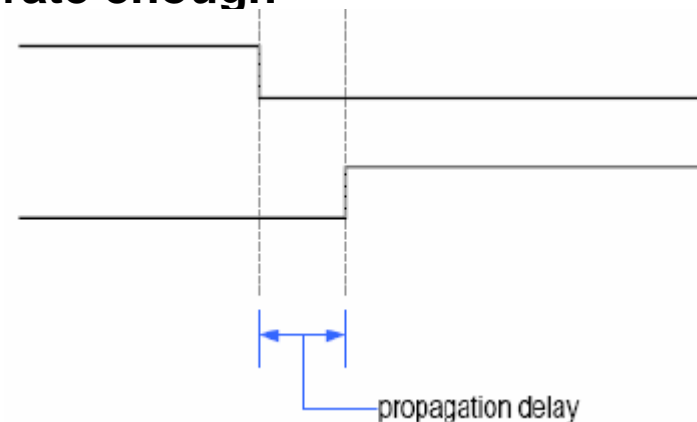
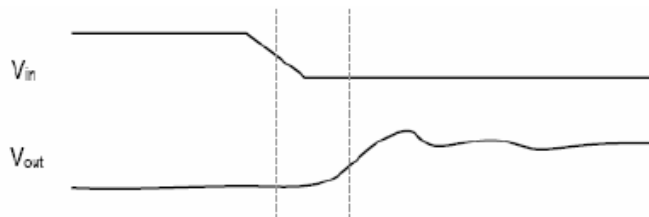


Intel Haswell (1.4B transistors)

?

## □ Abstraction: simplified model of a system

- Show the selected features accurate enough
- Ignore the others

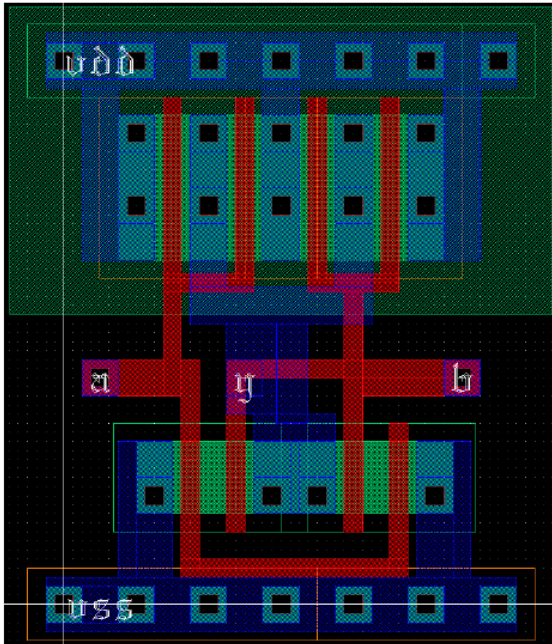




# VLSI Design Flow

## □ Evolution of circuit design

- Full-custom  $\Rightarrow$  Design-automation
  - *Based on library cells and IPs*
  - *Top-down methodology*
- Design abstraction  $\Rightarrow$  “Black box” or “Model”
  - *Parameter simplification*
  - *Accurate enough to meet the requirement*



```
module HS65_GH_NAND2AX14 (Z, A, B);  
    output Z;  
    input A,B;  
    not U1 (INTERNAL1, B) ;  
    or #1 U2 (Z, A, INTERNAL1) ;  
    specify  
        (A +=> Z) = (0.1,0.1);  
        (B -=> Z) = (0.1,0.1);  
    endspecify  
endmodule // HS65_GH_NAND2AX14
```



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## □ System Representation

## □ Design Flow

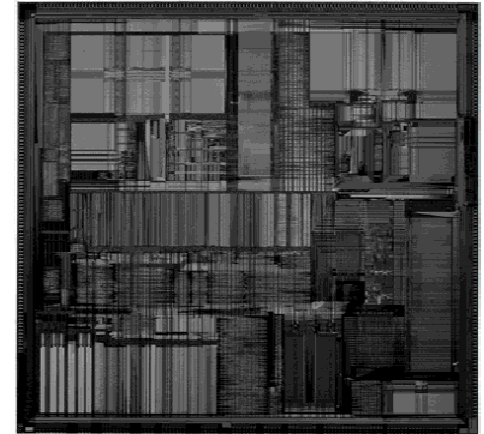
## □ RTL Basics



# VLSI Design

## □ Set of specification:

- What does the chip **do**?
- How **fast** does it run?
- How **reliable** will it be?
- How is the silicon **area**?
- How much **power** will it consume?
- .....



# VLSI Design Flow

- An iterative process that transfer the specification to a manufacturable chip through at least five levels of design abstraction.

Specification

Function, performance, definition:  
English

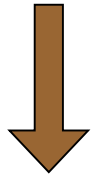


Behavior Design

Behavior, algorithm: C/C++, SystemC,  
Matlab ...

*Behavior simulation*

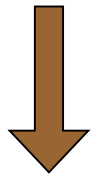
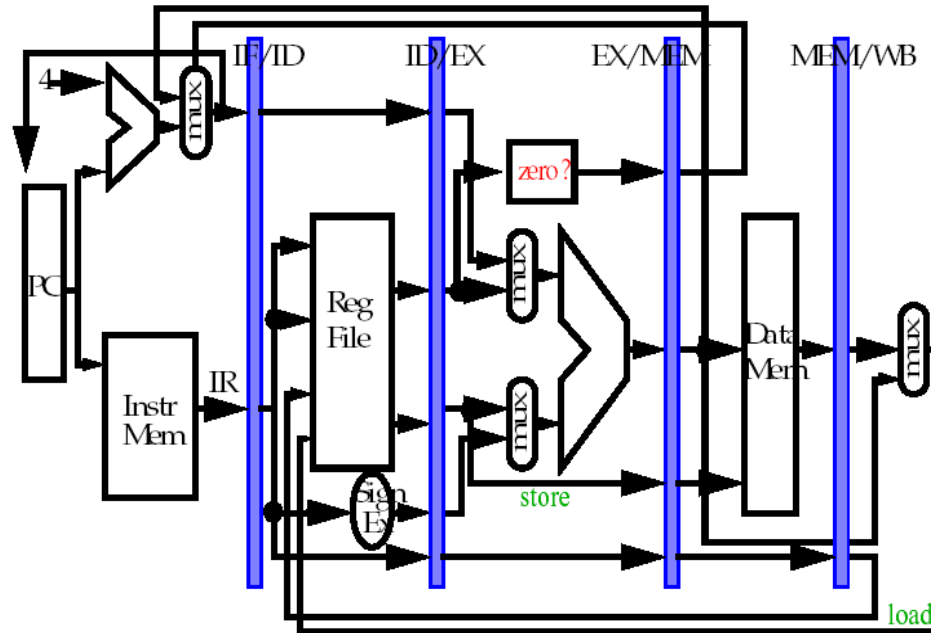




**VHDL**

**Register Transfer Level Design**

*RTL simulation*



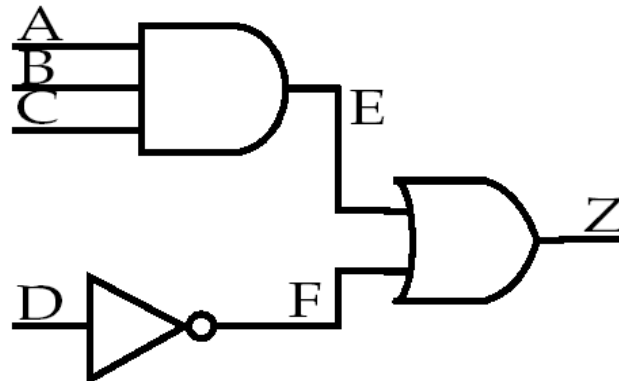
**Synthesis**

**Logic Design**

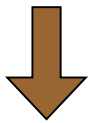
*Gate-level simulation*

*Timing analysis*

*Power analysis*

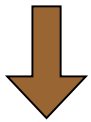
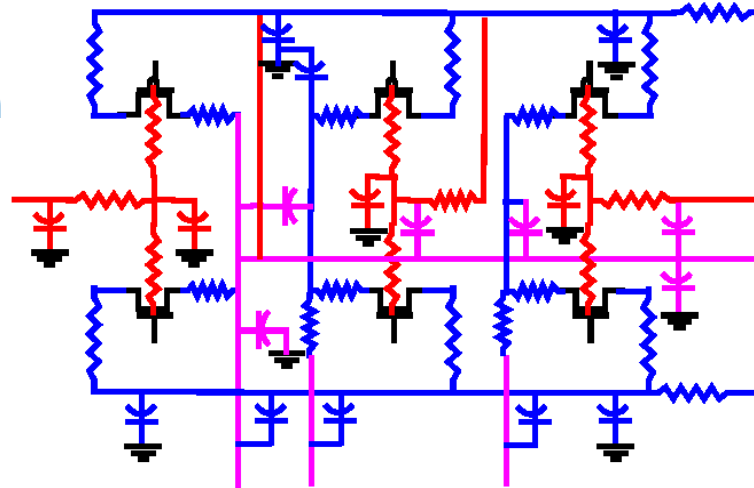






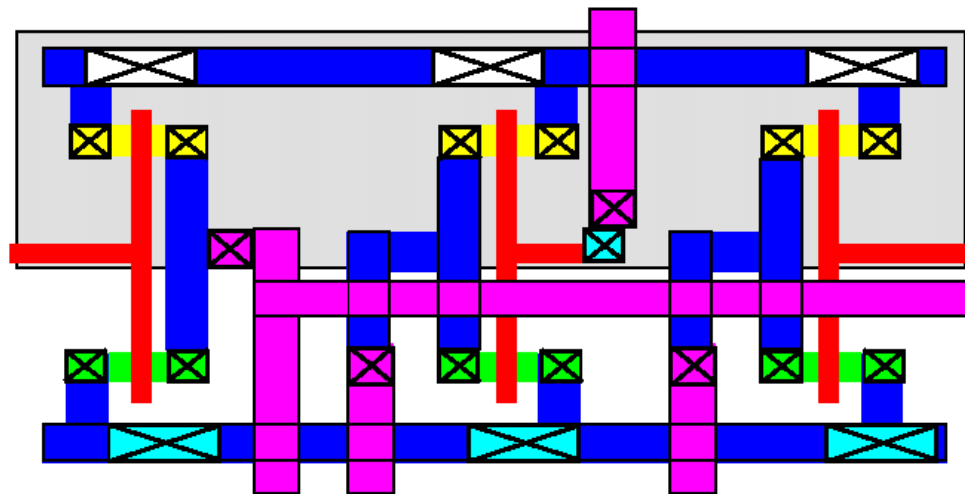
Custom Design

Circuit Design



Layout

Physical Design



*Design rule checking*  
*Post layout simulation*



# Verification

## □ Verification

- Check whether a design meets the **specification** and **performance goals**

## □ Two aspects

- **Functionality**
- **Performance (timing/power/area)**

## □ Method of Verification

- **Simulation**
  - *Spot check: cannot verify the absence of errors*
  - *Can be computation intensive*
- **Timing analysis**
  - *Just check delay*
- Formal verification
  - *Apply formal math techniques determine its property*
  - *E.g, equivalence checking*
- **Hardware emulation**



# Fabrication

## 22nm Fab Upgrades

D1D/C  
Oregon



Fab 32/12  
Arizona



Fab 28  
Israel



## 14nm and Beyond

D1X  
Oregon



Fab 42  
Arizona

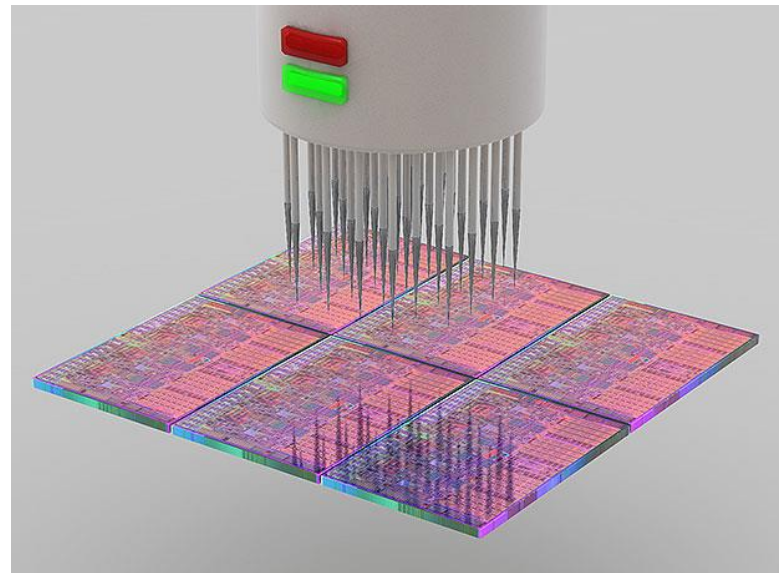


Fab 24  
Ireland



# Testing

- Testing is the process of detecting physical defects of a die or a package occurred at the time of manufacturing
- **Testing** and **verification** are different tasks.
- **Difficult for large circuit**
  - Need to add auxiliary testing circuit in design
  - E.g., built-in self test (BIST), scan chain etc.





# VLSI Design Flow: Tools

## □ Algorithm

- **Matlab**

## □ RTL Simulation

- **Modelsim, Mentor**
- VCS, Synopsys
- VerilogXL, Cadence

## □ Logic Synthesis

- **Design Compiler, Synopsys**
- Blast Create, Magma

## □ Transistor Simulation

- Hspice/Starsim, Synopsys
- Spectra, Cadence
- Eldo, Mentor

## □ Mixed-Signal Simulation

- **AMS Designer, Cadence**
- ADMS, Mentor
- Saber, Synopsys

## □ Place & Route

- Astro, Synopsys
- **Silicon Encounter, Cadence**
- Blast Fusion, Magma

## □ Layout

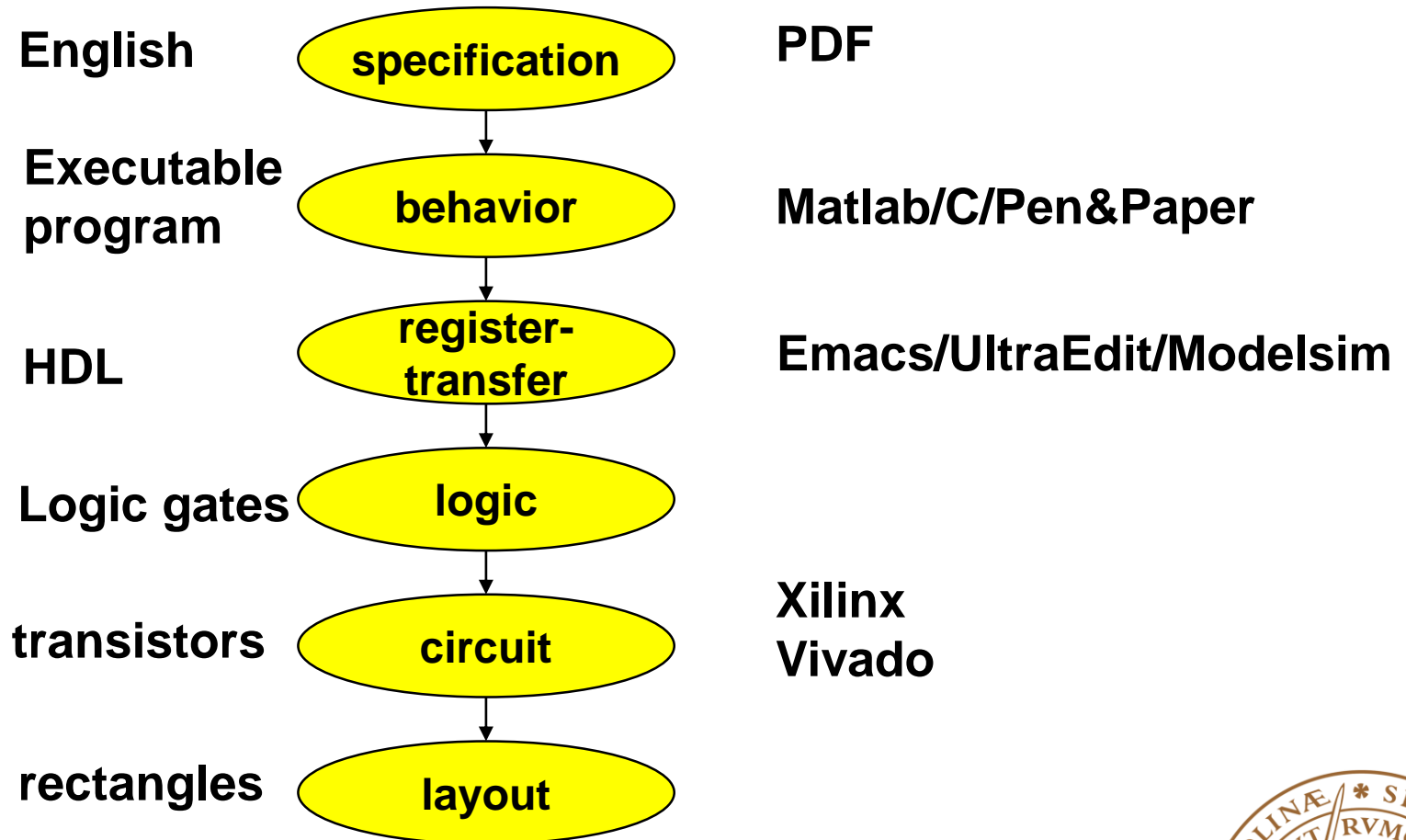
- **Icfb/Dracula, Cadence**
- ICstation/Calibre, Mentor

## □ FPGA

- **Vivado, Xilinx**
- Quatus, Altera



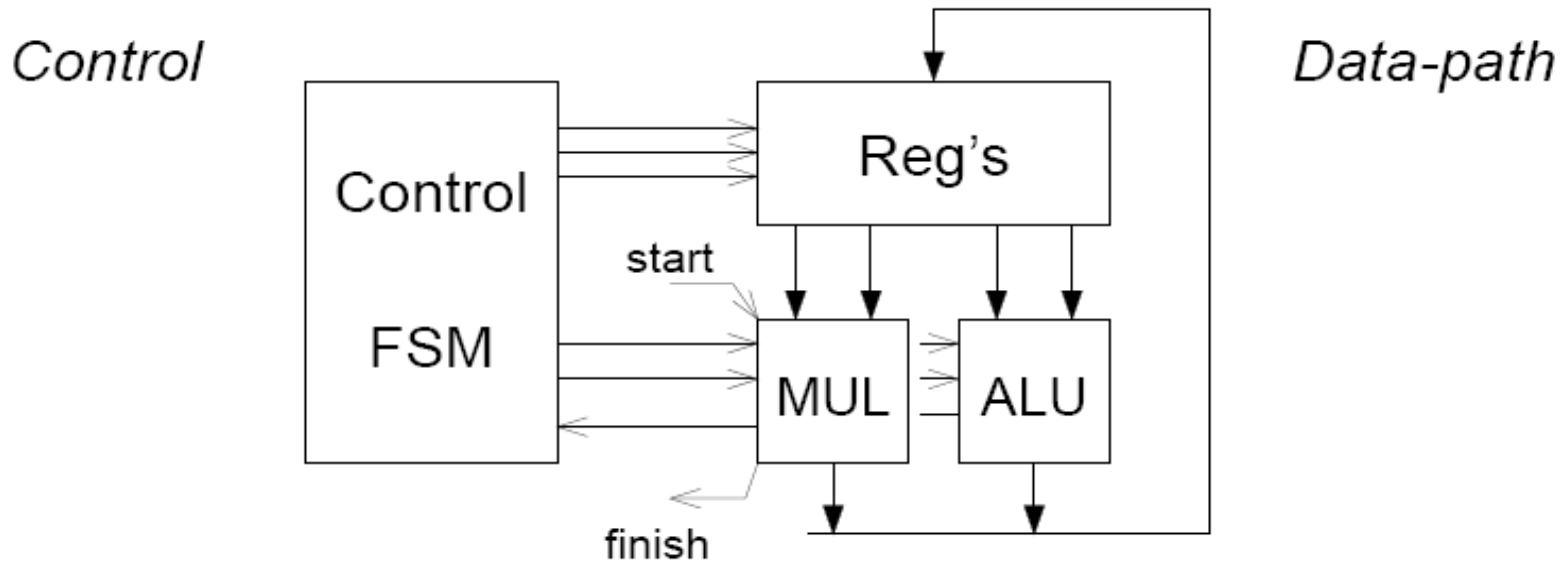
# VLSI Design Flow: Summary



***Following slides should fresh up your memory***



# Overall VLSI Structure



□ Scheduling / ordering / sequencing of operations

□ Mapping / allocation:

- Variables -> {Reg1, ... ,RegN}
- Operations -> {MUL, ADD, ALU, ... ,}

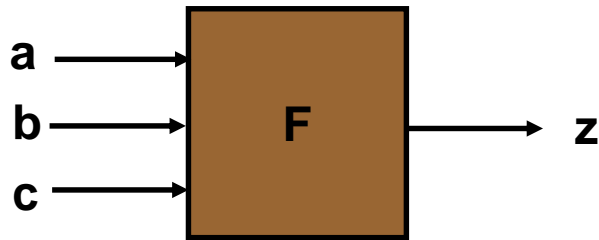
**We will implement something similar in this course**





# Two Basic Digital Components (What)

## Combinational Logic

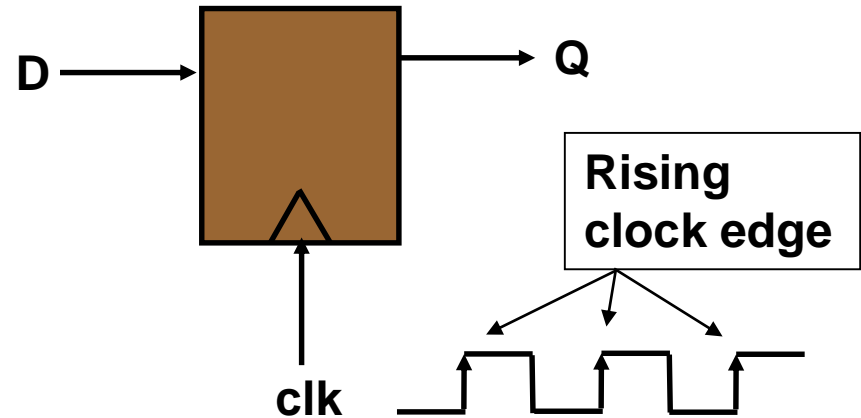


Always:

```
z <= F(a, b, c);
```

i.e. a function that is always evaluated when an input changes.  
Can be expressed by a truth table.

## Register



```
if clk' event and clk= '1' then  
  Q <= D;
```

i.e. a stored variable,  
Edge triggered D Flip-Flop  
with enable.



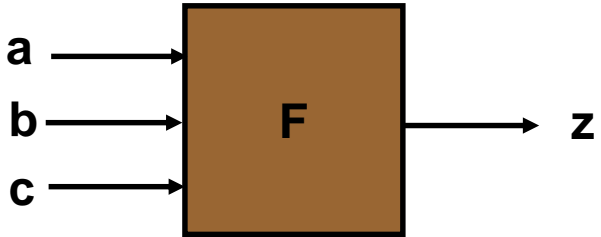
# Timing (When)

Only if we guarantee to meet the **timing requirements**

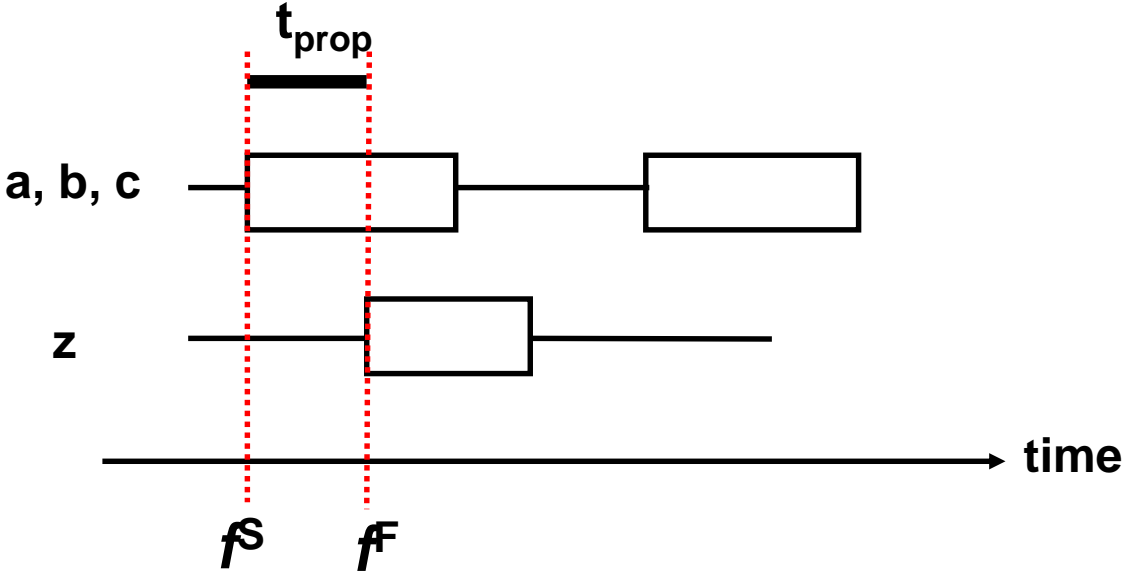
... do the components guarantee to behave as intended.



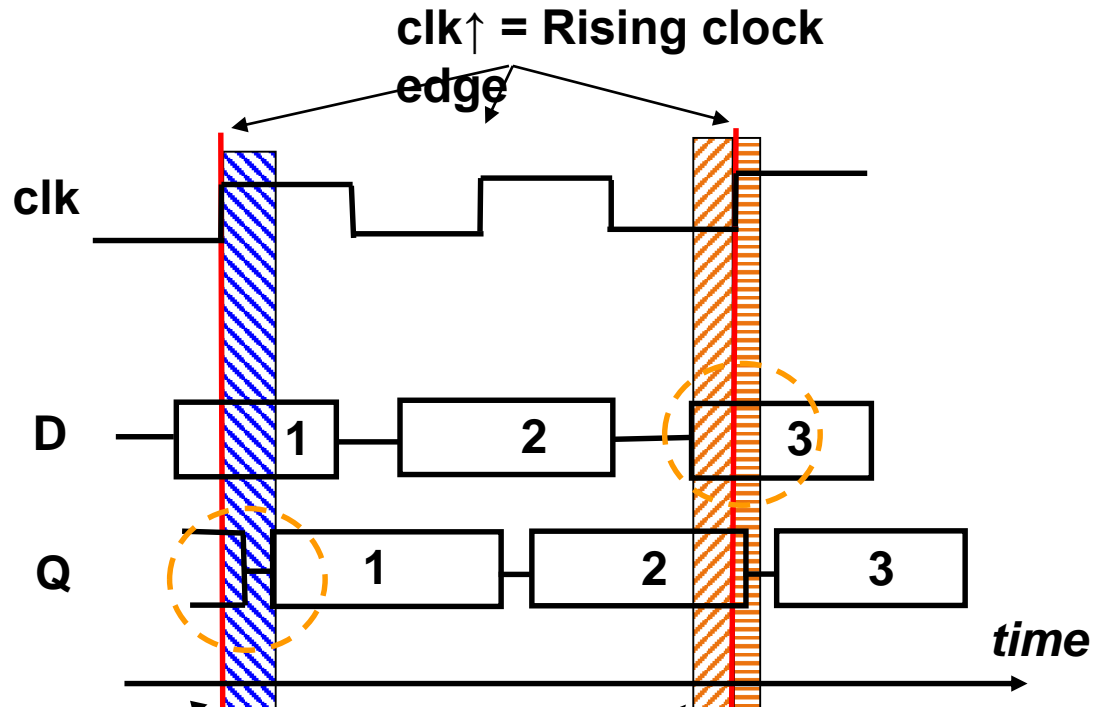
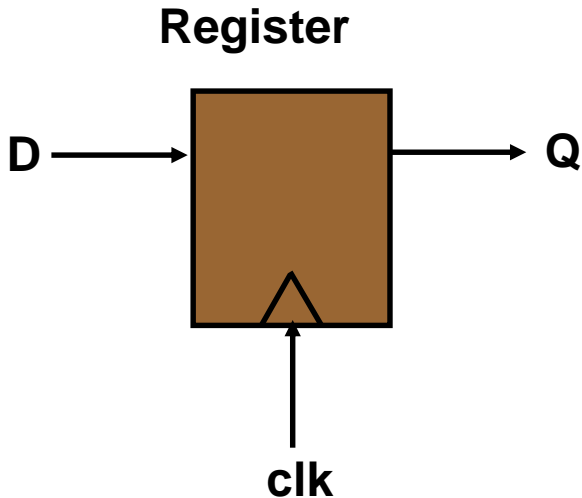
# Combinational Logic Timing



- **Propagation delay:**  
After presenting new inputs  
Worst case delay before  
producing correct output



# Register timing



**Propagation delay (clk\_to\_Q):**  
Worst case (maximum) delay after  $\text{clk}\uparrow$  before new output data is valid on Q.

**Setup time:** Minimum time input must be stable before  $\text{clk}\uparrow$

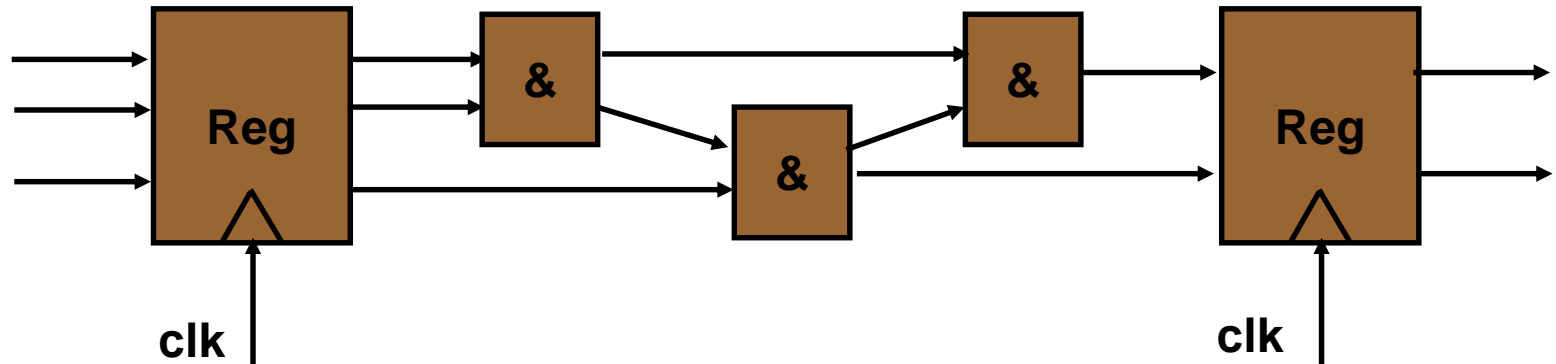
**Hold time:** Minimum time input must be stable after  $\text{clk}\uparrow$





# Clock Frequency (RTL)

□ What is the maximum clock frequency?



## Register

Propagation delay:	T <sub>clk-Q</sub>	250ps
Setup time:	T <sub>su</sub>	200ps
Hold time:	T <sub>h</sub>	100ps

## AND-gate

Propagation delay:	T <sub>prop</sub>	250ps
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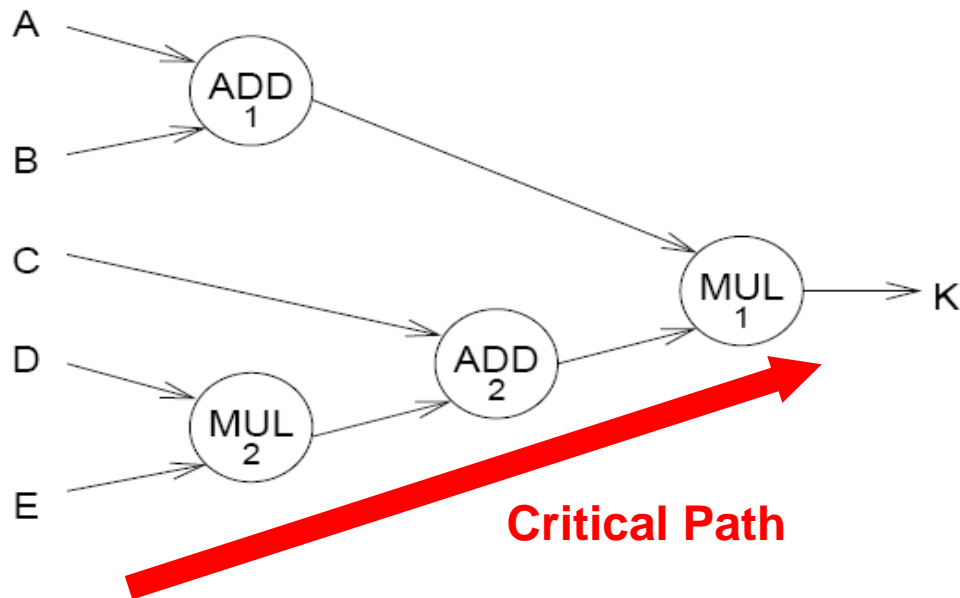
$$250 + 250 \times 3 + 200 = 1.2\text{ns}$$

$$f = 833\text{MHz}$$



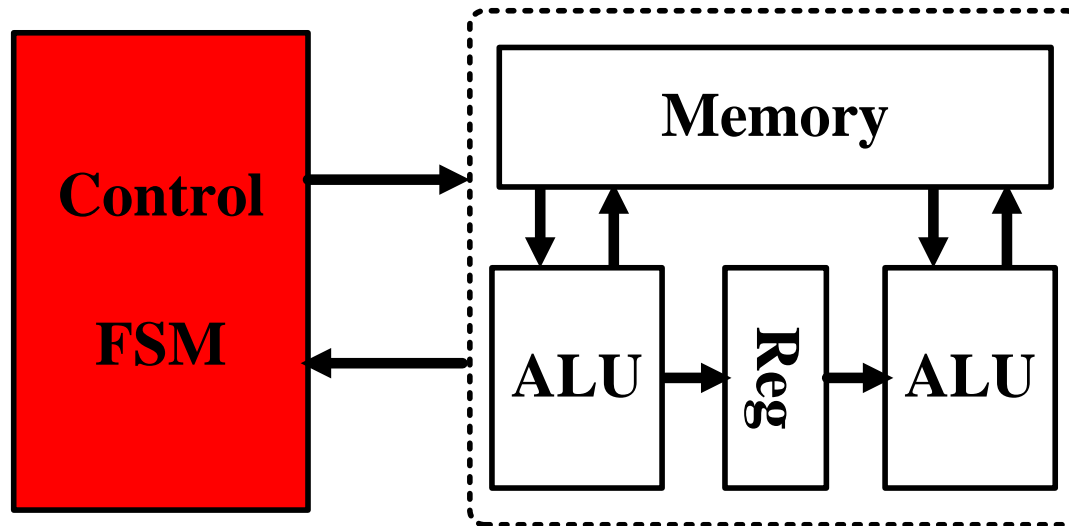
# Critical path

- ...begin to explore the construction of digital systems with complex behavior
  - Example:  $K = (A +_1 B) *_1 (C +_2 D *_2 E)$
- Combinational circuit:



# Tomorrow

- 08:15-10:00 in E:3308
- The controller: Finite State Machine
- VHDL Basics
- Assignment 1



# Thanks

